

## REFERENCES

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13. Data Sheet DM74LS244

## APPENDICES

### APPENDIX (A)

#### VHDL Programming

```
---ma=0.6, mf=21
LIBRARY IEEE;
USE IEEE.STD_LOGIC_1164.ALL;
USE IEEE.STD_LOGIC_ARITH.ALL;
USE IEEE.STD_LOGIC_UNSIGNED.ALL;

ENTITY PWM IS
PORT
(
CLOCK_25MHZ:IN STD_LOGIC;
---CLOCK_1M,CLOCK_100K: OUT STD_LOGIC;
---COUNT1:OUT STD_LOGIC_VECTOR (7 DOWNTO 0);--MAIN COUNTER 1 TO 6
---STATE:OUT STD_LOGIC_VECTOR (11 DOWNTO 0);--OUT INTEGER RANGE 1 TO 36

CLOCK_1,CLOCK_2:OUT STD_LOGIC);
END PWM;

ARCHITECTURE A OF PWM IS
SIGNAL COUNT_100KHZ: STD_LOGIC_VECTOR(2 DOWNTO 0);
SIGNAL COUNT_1MHZ: STD_LOGIC_VECTOR(4 DOWNTO 0);
SIGNAL CLOCK_1MHZ_INT, CLOCK_100KHZ_INT: STD_LOGIC;

SIGNAL CYCLE1,CYCLE2: STD_LOGIC_VECTOR(7 DOWNTO 0);
SIGNAL COUNT_1,COUNT_2:STD_LOGIC_VECTOR(7 DOWNTO 0);
SIGNAL COUNT:STD_LOGIC_VECTOR(11 DOWNTO 0); ---INTEGER RANGE 1 TO 36
---MMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMMM
SIGNAL CLOCK_1_INT,CLOCK_2_INT:STD_LOGIC;
SIGNAL
DATA1,DATA2,DATA3,DATA4,DATA5,DATA6,DATA7,DATA8,DATA9,DATA10:STD_LOGIC_V
ECTOR(11 DOWNTO 0);
SIGNAL
DATA11,DATA12,DATA13,DATA14,DATA15,DATA16,DATA17,DATA18,DATA19,DATA20:STD
_LOGIC_VECTOR(11 DOWNTO 0);
SIGNAL
DATA21,DATA22,DATA23,DATA24,DATA25,DATA26,DATA27,DATA28,DATA29,DATA30:STD
_LOGIC_VECTOR(11 DOWNTO 0);
SIGNAL
DATA31,DATA32,DATA33,DATA34,DATA35,DATA36,DATA37,DATA38,DATA39,DATA40:STD
_LOGIC_VECTOR(11 DOWNTO 0);
SIGNAL
DU1,DU2,DU3,DU4,DU5,DU6,DU7,DU8,DU9,DU10,DU11,DU12,DU13,DU14,DU15:STD_LOGIC_V
ECTOR(7 DOWNTO 0);
```

```

SIGNAL
DU16,DU17,DU18,DU19,DU20,DU21,DU22,DU23,DU24,DU25,DU26,DU27,DU28:STD_LOGIC_VE
CTOR(7 DOWNT0 0);
SIGNAL
DU29,DU30,DU31,DU32,DU33,DU34,DU35,DU36,DU37,DU38,DU39,DU40:STD_LOGIC_VECTOR
(7 DOWNT0 0);

```

```

BEGIN

```

```

-----
DATA1<=X"032";      DU1<=X"06";
DATA2<=X"064";      DU2<=X"09";
DATA3<=X"096";      DU3<=X"0E";
DATA4<=X"0C8";      DU4<=X"12";
DATA5<=X"0FA";      DU5<=X"15";
DATA6<=X"12C";      DU6<=X"19";
DATA7<=X"15E";      DU7<=X"1B";
DATA8<=X"190";      DU8<=X"1D";
DATA9<=X"1C2";      DU9<=X"1E";
DATA10<=X"1F4";     DU10<=X"1E";
DATA11<=X"226";     DU11<=X"1E";
DATA12<=X"258";     DU12<=X"1D";
DATA13<=X"28A";     DU13<=X"1B";
DATA14<=X"2BC";     DU14<=X"19";
DATA15<=X"2EE";     DU15<=X"15";
DATA16<=X"320";     DU16<=X"12";
DATA17<=X"352";     DU17<=X"0E";
DATA18<=X"384";     DU18<=X"09";
DATA19<=X"3B6";     DU19<=X"06";
DATA20<=X"3E8";     DU20<=X"00";

```

```

-----
DATA21<=X"41A";     DU21<=X"06";
DATA22<=X"44C";     DU22<=X"09";
DATA23<=X"47E";     DU23<=X"0E";
DATA24<=X"4B0";     DU24<=X"12";
DATA25<=X"4E2";     DU25<=X"15";
DATA26<=X"514";     DU26<=X"19";
DATA27<=X"546";     DU27<=X"1B";
DATA28<=X"578";     DU28<=X"1D";
DATA29<=X"5AA";     DU29<=X"1E";
DATA30<=X"5DC";     DU30<=X"1E";
DATA31<=X"60E";     DU31<=X"1E";
DATA32<=X"640";     DU32<=X"1D";
DATA33<=X"672";     DU33<=X"1B";
DATA34<=X"6A4";     DU34<=X"19";
DATA35<=X"6D6";     DU35<=X"15";
DATA36<=X"708";     DU36<=X"12";
DATA37<=X"73A";     DU37<=X"0E";
DATA38<=X"76C";     DU38<=X"09";
DATA39<=X"79E";     DU39<=X"06";
DATA40<=X"7D0";     DU40<=X"00";
--DATA41<=X"802";   DU41<=X"";
--CLOCK_1M<=CLOCK_1MHZ_INT;
--CLOCK_100K<=CLOCK_100KHZ_INT;

```

```

PROCESS

```

```

BEGIN

```

```

WAIT UNTIL CLOCK_25MHZ'EVENT AND CLOCK_25MHZ='1';
IF COUNT_1MHZ < 47 THEN
COUNT_1MHZ <= COUNT_1MHZ+1;
ELSE

```

```

COUNT_1MHZ <= "00000";
END IF;
IF COUNT_1MHZ <24 THEN
CLOCK_1MHZ_INT <= '0';
ELSE
CLOCK_1MHZ_INT <= '1';
END IF;
END PROCESS;

PROCESS
BEGIN
WAIT UNTIL CLOCK_1MHZ_INT'EVENT AND CLOCK_1MHZ_INT='1';
IF COUNT_100KHZ /= 4 THEN
COUNT_100KHZ<= COUNT_100KHZ+1;
ELSE
COUNT_100KHZ<="000";
CLOCK_100KHZ_INT<= NOT CLOCK_100KHZ_INT;
END IF;
END PROCESS;

PROCESS
BEGIN
--WAIT UNTIL CLOCK_100KHZ_INT'EVENT AND CLOCK_100KHZ_INT='1';

WAIT UNTIL CLOCK_25MHZ'EVENT AND CLOCK_25MHZ='1';
IF COUNT <2000 THEN ----SAMPLE 10 CYCLE PER CHANNEL
COUNT<= COUNT+1;
ELSE
COUNT<="000000000001";
END IF;
-----STATE<=COUNT;

IF COUNT=DATA40 OR COUNT<DATA1 THEN ---00--10
CYCLE1<=DU1; CYCLE2<="00000000";---1
ELSIF COUNT >= DATA1 AND COUNT < DATA2 THEN ---10--20
CYCLE1<=DU2; CYCLE2<="00000000";---2
ELSIF COUNT >= DATA2 AND COUNT<DATA3 THEN--20--30
CYCLE1<=DU3; CYCLE2<="00000000";---3
ELSIF COUNT >= DATA3 AND COUNT<DATA4 THEN--20--30
CYCLE1<=DU4; CYCLE2<="00000000";---4
ELSIF COUNT >= DATA4 AND COUNT<DATA5 THEN--10--20
CYCLE1<=DU5; CYCLE2<="00000000";---3
ELSIF COUNT >= DATA5 AND COUNT<DATA6 THEN--20--30
CYCLE1<=DU6; CYCLE2<="00000000";---2
ELSIF COUNT >= DATA6 AND COUNT<DATA7 THEN--10--20
CYCLE1<=DU7; CYCLE2<="00000000";---1
ELSIF COUNT >= DATA7 AND COUNT<DATA8 THEN--00--10
CYCLE1<=DU8; CYCLE2<="00000000";---1
ELSIF COUNT >= DATA8 AND COUNT<DATA9 THEN--10--20
CYCLE1<=DU9; CYCLE2<="00000000";---2
ELSIF COUNT >= DATA9 AND COUNT<DATA10 THEN--20--30
CYCLE1<=DU10; CYCLE2<="00000000";---3
-----
ELSIF COUNT >= DATA10 AND COUNT<DATA11 THEN
CYCLE1<=DU11; CYCLE2<="00000000";---4
-----
ELSIF COUNT >= DATA11 AND COUNT<DATA12 THEN--10--20
CYCLE1<=DU12; CYCLE2<="00000000";---3
ELSIF COUNT >= DATA12 AND COUNT<DATA13 THEN--20--30
CYCLE1<=DU13; CYCLE2<="00000000";---3

```

```

ELSIF COUNT >= DATA13 AND COUNT<DATA14 THEN--10--20
    CYCLE1<=DU14; CYCLE2<="00000000";--2
ELSIF COUNT >= DATA14 AND COUNT<DATA15 THEN--00--10
    CYCLE1<=DU15; CYCLE2<="00000000";--1
ELSIF COUNT >= DATA15 AND COUNT<DATA16 THEN--10--20
    CYCLE1<=DU16; CYCLE2<="00000000";--1
ELSIF COUNT >= DATA16 AND COUNT<DATA17 THEN--20--30
    CYCLE1<=DU17; CYCLE2<="00000000";--2
ELSIF COUNT >= DATA17 AND COUNT<DATA18 THEN--10--20
    CYCLE1<=DU18; CYCLE2<="00000000";--3
ELSIF COUNT >= DATA18 AND COUNT<DATA19 THEN--20--30
    CYCLE1<=DU19; CYCLE2<="00000000";--4
ELSIF COUNT >= DATA19 AND COUNT<DATA20 THEN--20--30
    CYCLE1<=DU20; CYCLE2<="00000000";--3

```

```

-----
ELSIF COUNT >= DATA20 AND COUNT<DATA21 THEN--10--20
    CYCLE2<=DU21; CYCLE1<="00000000";--2
ELSIF COUNT >= DATA21 AND COUNT<DATA22 THEN--00--10
    CYCLE2<=DU22; CYCLE1<="00000000";--1
ELSIF COUNT >= DATA22 AND COUNT<DATA23 THEN--10--20
    CYCLE2<=DU23; CYCLE1<="00000000";--2
ELSIF COUNT >= DATA23 AND COUNT<DATA24 THEN--20--30
    CYCLE2<=DU24; CYCLE1<="00000000";--3
ELSIF COUNT >= DATA24 AND COUNT<DATA25 THEN--20--30
    CYCLE2<=DU25; CYCLE1<="00000000";--4
ELSIF COUNT >= DATA25 AND COUNT<DATA26 THEN--10--20
    CYCLE2<=DU26; CYCLE1<="00000000";--3
ELSIF COUNT >= DATA26 AND COUNT<DATA27 THEN--20--30
    CYCLE2<=DU27; CYCLE1<="00000000";--2
ELSIF COUNT >= DATA27 AND COUNT<DATA28 THEN--10--20
    CYCLE2<=DU28; CYCLE1<="00000000";--1
ELSIF COUNT >= DATA28 AND COUNT<DATA29 THEN--00--10
    CYCLE2<=DU29; CYCLE1<="00000000";--1
ELSIF COUNT >= DATA29 AND COUNT<DATA30 THEN--10--20
    CYCLE2<=DU30; CYCLE1<="00000000";--2
ELSIF COUNT >= DATA30 AND COUNT<DATA31 THEN--20--30
    CYCLE2<=DU31; CYCLE1<="00000000";--3

```

```

-----
ELSIF COUNT >= DATA31 AND COUNT<DATA32 THEN--20--30
    CYCLE2<=DU32; CYCLE1<="00000000";--4

```

```

-----
ELSIF COUNT >= DATA32 AND COUNT<DATA33 THEN--10--20
    CYCLE2<=DU33; CYCLE1<="00000000";--3
ELSIF COUNT >= DATA33 AND COUNT<DATA34 THEN--20--30
    CYCLE2<=DU34; CYCLE1<="00000000";--3
ELSIF COUNT >= DATA34 AND COUNT<DATA35 THEN--10--20
    CYCLE2<=DU35; CYCLE1<="00000000";--2
ELSIF COUNT >= DATA35 AND COUNT<DATA36 THEN--00--10
    CYCLE2<=DU36; CYCLE1<="00000000";--1
ELSIF COUNT >= DATA36 AND COUNT<DATA37 THEN--10--20
    CYCLE2<=DU37; CYCLE1<="00000000";--1
ELSIF COUNT >= DATA37 AND COUNT<DATA38 THEN--20--30
    CYCLE2<=DU38; CYCLE1<="00000000";--2
ELSIF COUNT >= DATA38 AND COUNT<DATA39 THEN--10--20
    CYCLE2<=DU39; CYCLE1<="00000000";--3
ELSIF COUNT >= DATA39 AND COUNT<DATA40 THEN--20--30
    CYCLE2<=DU40; CYCLE1<="00000000";--4

```

```

END IF;
END PROCESS;

```

```

-----
PROCESS
BEGIN
----WAIT UNTIL CLOCK_100KHZ_INTEVENT AND CLOCK_100KHZ_INT='1';
WAIT UNTIL CLOCK_25MHZ'EVENT AND CLOCK_25MHZ='1';

```

```

-----
IF COUNT_1<50 THEN
COUNT_1<=COUNT_1+1;
ELSE
COUNT_1<="00000001";
END IF;
--COUNT1<=COUNT_1;---TRACE OUTPUT

```

```

-----C1-----
IF COUNT_1<= CYCLE1 THEN
CLOCK_1_INT<='1';
ELSE
CLOCK_1_INT<='0';
END IF;
CLOCK_1<=CLOCK_1_INT;-----OUTPUT

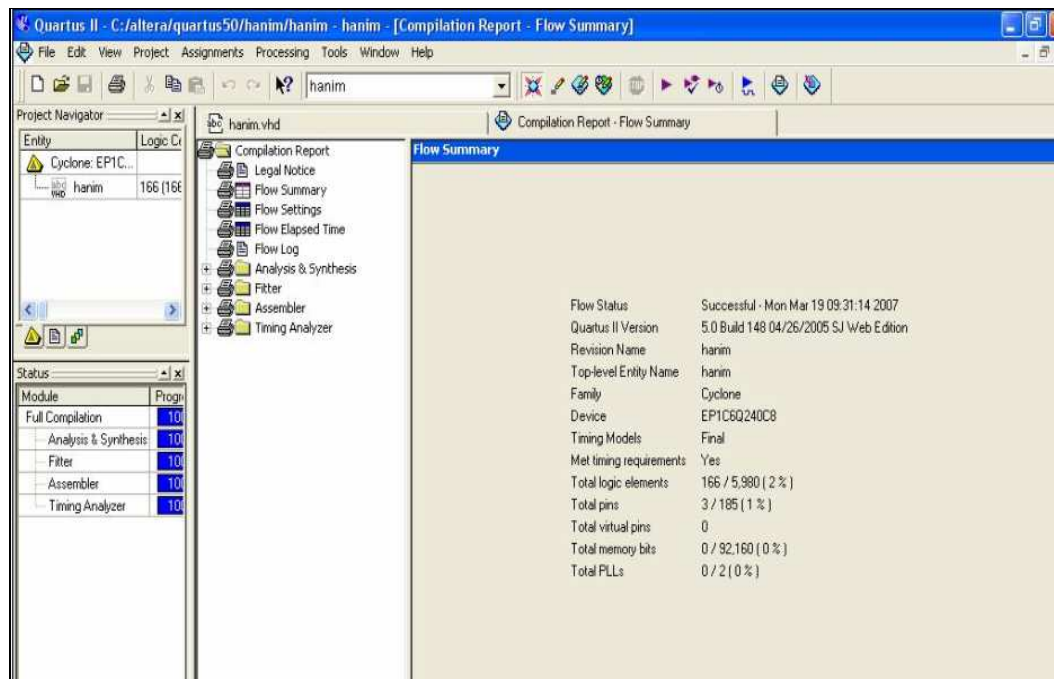
```

```

-----C2-----
IF COUNT_1 <=CYCLE2 THEN
CLOCK_2_INT<='1';
ELSE
CLOCK_2_INT<='0';
END IF;
CLOCK_2<=CLOCK_2_INT;---OUTPUT
END PROCESS;
END A;

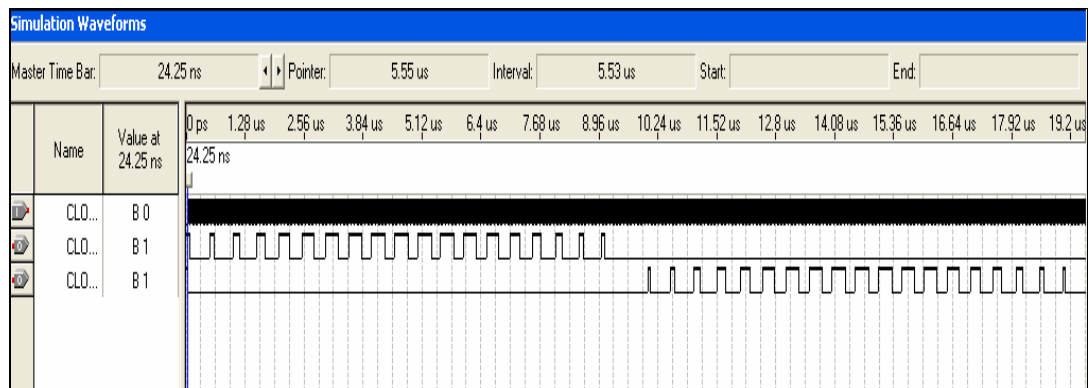
```

## APPENDIX A (i)



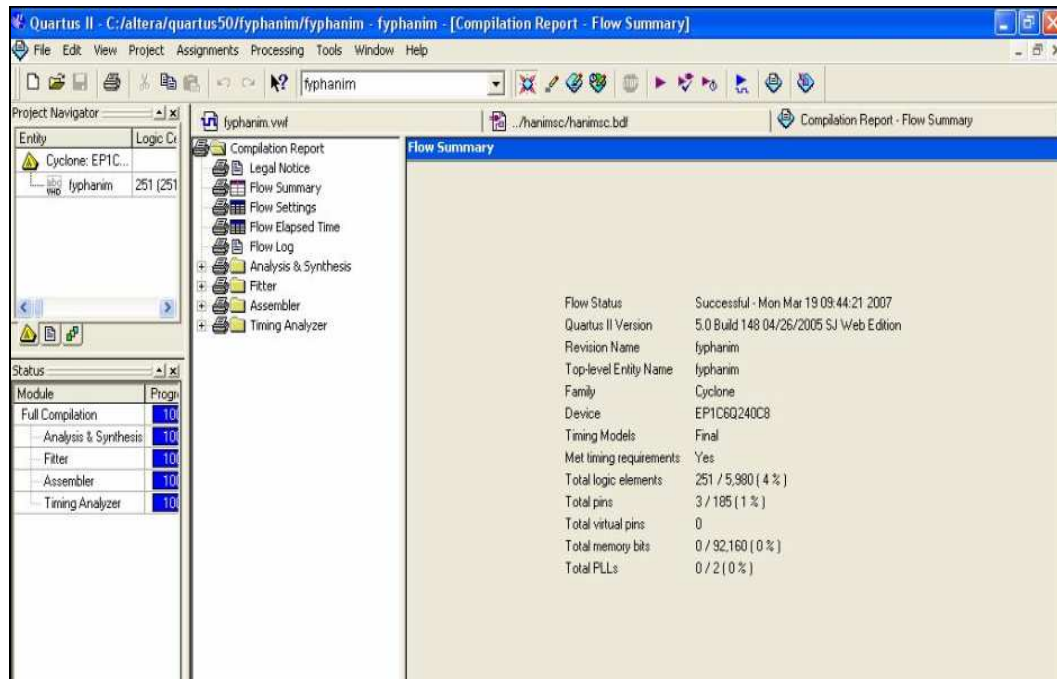
Flow summary after done the compilation of VHDL Programming

## APPENDIX A (ii)



Simulation waveform after completed the VHDL Programming

## APPENDIX A (iii)



The screenshot displays the Quartus II interface with the 'Flow Summary' report open. The report provides a detailed overview of the compilation process, including the status, version, and resource usage.

Property	Value
Flow Status	Successful - Mon Mar 19 09:44:21 2007
Quartus II Version	5.0 Build 148 04/26/2005 SJ Web Edition
Revision Name	fyphanim
Top-level Entity Name	fyphanim
Family	Cyclone
Device	EP1C6Q240C8
Timing Models	Final
Met timing requirements	Yes
Total logic elements	251 / 5,980 (4 %)
Total pins	3 / 185 (1 %)
Total virtual pins	0
Total memory bits	0 / 92,160 (0 %)
Total PLLs	0 / 2 (0 %)

Flow summary after done the compilation of Block Diagram



## DM74LS244 Octal 3-STATE Buffer/Line Driver/Line Receiver

### General Description

These buffers/line drivers are designed to improve both the performance and PC board density of 3-STATE buffers/drivers employed as memory-address drivers, clock drivers, and bus-oriented transmitters/receivers. Featuring 400 mV of hysteresis at each low current PNP data line input, they provide improved noise rejection and high fanout outputs and can be used to drive terminated lines down to 133Ω.

### Features

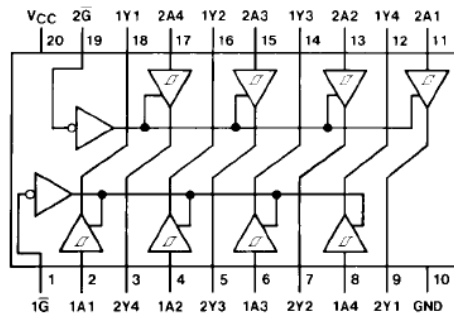
- 3-STATE outputs drive bus lines directly
- PNP inputs reduce DC loading on bus lines
- Hysteresis at data inputs improves noise margins
- Typical  $I_{OL}$  (sink current) 24 mA
- Typical  $I_{OH}$  (source current) -15 mA
- Typical propagation delay times
  - Inverting 10.5 ns
  - Noninverting 12 ns
- Typical enable/disable time 18 ns
- Typical power dissipation (enabled)
  - Inverting 130 mW
  - Noninverting 135 mW

### Ordering Code:

Order Number	Package Number	Package Description
DM74LS244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
DM74LS244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74LS244N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Connection Diagram



### Function Table

Inputs		Output
$\overline{G}$	A	Y
L	L	L
L	H	H
H	X	Z

L = LOW Logic Level  
H = HIGH Logic Level  
X = Either LOW or HIGH Logic Level  
Z = High Impedance

**Absolute Maximum Ratings**(Note 1)

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	0°C to +70°C
Storage Temperature Range	-65°C to +150°C

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

**Recommended Operating Conditions**

Symbol	Parameter	Min	Nom	Max	Units
V <sub>CC</sub>	Supply Voltage	4.75	5	5.25	V
V <sub>IH</sub>	HIGH Level Input Voltage	2			V
V <sub>IL</sub>	LOW Level Input Voltage			0.8	V
I <sub>OH</sub>	HIGH Level Output Current			-15	mA
I <sub>OL</sub>	LOW Level Output Current			24	mA
T <sub>A</sub>	Free Air Operating Temperature	0		70	°C

**Electrical Characteristics**

over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ (Note 2)	Max	Units	
V <sub>I</sub>	Input Clamp Voltage	V <sub>CC</sub> = Min, I <sub>I</sub> = -18 mA			-1.5	V	
HYS	Hysteresis (V <sub>T+</sub> - V <sub>T-</sub> ) Data Inputs Only	V <sub>CC</sub> = Min	0.2	0.4		V	
V <sub>OH</sub>	HIGH Level Output Voltage	V <sub>CC</sub> = Min, V <sub>IH</sub> = Min V <sub>IL</sub> = Max, I <sub>OH</sub> = -1 mA	2.7			V	
		V <sub>CC</sub> = Min, V <sub>IH</sub> = Min V <sub>IL</sub> = Max, I <sub>OH</sub> = -3 mA	2.4	3.4			
		V <sub>CC</sub> = Min, V <sub>IH</sub> = Min V <sub>IL</sub> = 0.5V, I <sub>OH</sub> = Max	2				
V <sub>OL</sub>	LOW Level Output Voltage	V <sub>CC</sub> = Min V <sub>IL</sub> = Max V <sub>IH</sub> = Min	I <sub>OL</sub> = 12 mA I <sub>OL</sub> = Max		0.4 0.5	V	
I <sub>OZH</sub>	Off-State Output Current, HIGH Level Voltage Applied	V <sub>CC</sub> = Max V <sub>IL</sub> = Max	V <sub>O</sub> = 2.7V		20	μA	
I <sub>OZL</sub>	Off-State Output Current, LOW Level Voltage Applied	V <sub>IH</sub> = Min	V <sub>O</sub> = 0.4V		-20	μA	
I <sub>I</sub>	Input Current at Maximum Input Voltage	V <sub>CC</sub> = Max	V <sub>I</sub> = 7V		0.1	mA	
I <sub>IH</sub>	HIGH Level Input Current	V <sub>CC</sub> = Max	V <sub>I</sub> = 2.7V		20	μA	
I <sub>IL</sub>	LOW Level Input Current	V <sub>CC</sub> = Max	V <sub>I</sub> = 0.4V	-0.5	-200	μA	
I <sub>OS</sub>	Short Circuit Output Current	V <sub>CC</sub> = Max (Note 3)		-40	-225	mA	
I <sub>CC</sub>	Supply Current	V <sub>CC</sub> = Max, Outputs Open	Outputs HIGH		13	23	mA
			Outputs LOW		27	46	
			Outputs Disabled		32	54	

Note 2: All typicals are at V<sub>CC</sub> = 5V, T<sub>A</sub> = 25°C.

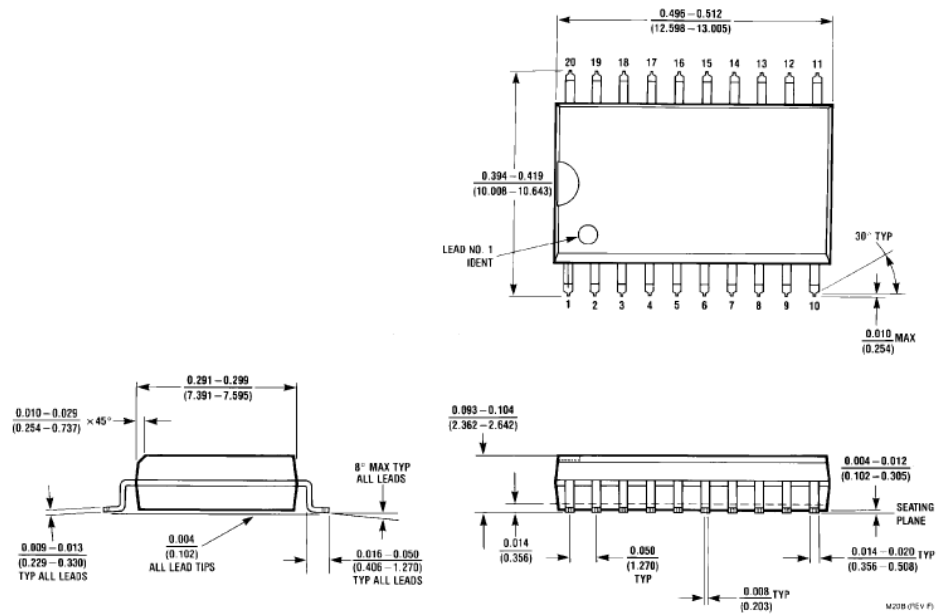
Note 3: Not more than one output should be shorted at a time, and the duration should not exceed one second.

## Switching Characteristics

at  $V_{CC} = 5V$ ,  $T_A = 25^\circ C$

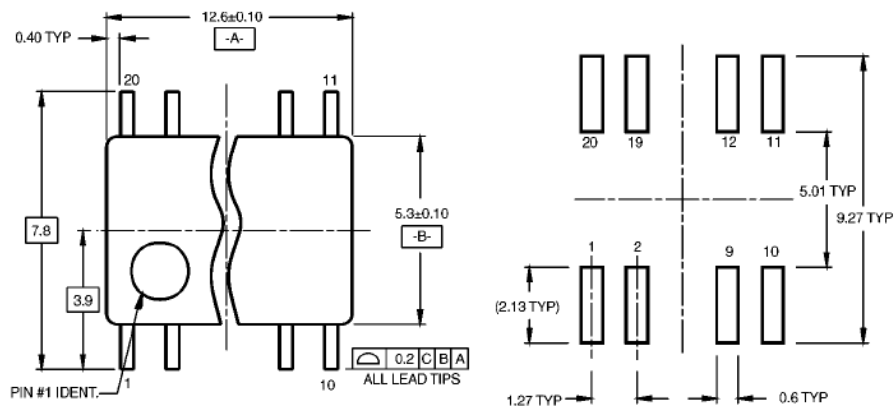
Symbol	Parameter	Conditions	Max	Units
$t_{PLH}$	Propagation Delay Time LOW-to-HIGH Level Output	$C_L = 45 \text{ pF}$ $R_L = 667\Omega$	18	ns
$t_{PHL}$	Propagation Delay Time HIGH-to-LOW Level Output	$C_L = 45 \text{ pF}$ $R_L = 667\Omega$	18	ns
$t_{PZL}$	Output Enable Time to LOW Level	$C_L = 45 \text{ pF}$ $R_L = 667\Omega$	30	ns
$t_{PZH}$	Output Enable Time to HIGH Level	$C_L = 45 \text{ pF}$ $R_L = 667\Omega$	23	ns
$t_{PLZ}$	Output Disable Time from LOW Level	$C_L = 5 \text{ pF}$ $R_L = 667\Omega$	25	ns
$t_{PHZ}$	Output Disable Time from HIGH Level	$C_L = 5 \text{ pF}$ $R_L = 667\Omega$	18	ns
$t_{PLH}$	Propagation Delay Time LOW-to-HIGH Level Output	$C_L = 150 \text{ pF}$ $R_L = 667\Omega$	21	ns
$t_{PHL}$	Propagation Delay Time HIGH-to-LOW Level Output	$C_L = 150 \text{ pF}$ $R_L = 667\Omega$	22	ns
$t_{PZL}$	Output Enable Time to LOW Level	$C_L = 150 \text{ pF}$ $R_L = 667\Omega$	33	ns
$t_{PZH}$	Output Enable Time to HIGH Level	$C_L = 150 \text{ pF}$ $R_L = 667\Omega$	26	ns

**Physical Dimensions** inches (millimeters) unless otherwise noted

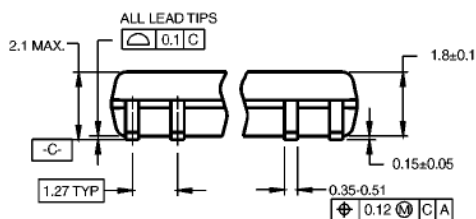


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M20B**

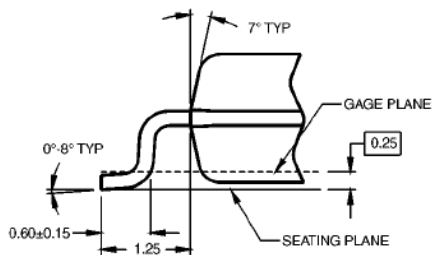
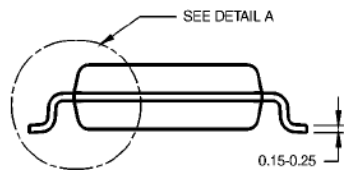
**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**LAND PATTERN RECOMMENDATION**



DIMENSIONS ARE IN MILLIMETERS



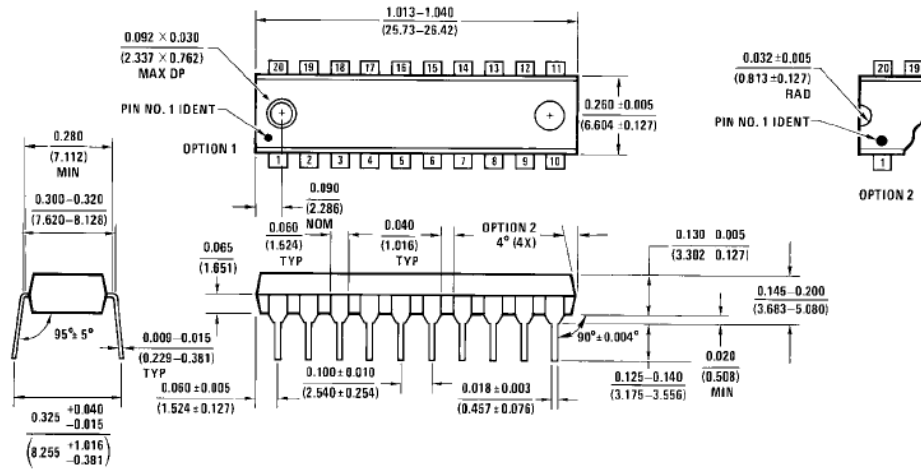
**DETAIL A**

- NOTES:  
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
 Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N20A

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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# IRF840

## N - CHANNEL 500V - 0.75Ω - 8A - TO-220 PowerMESH™ MOSFET

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
IRF840	500 V	< 0.85 Ω	8 A

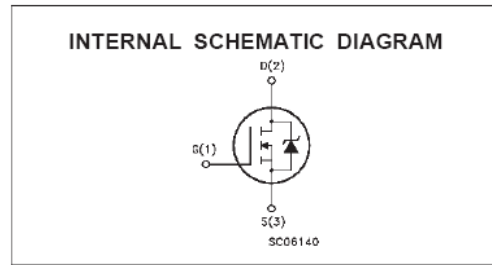
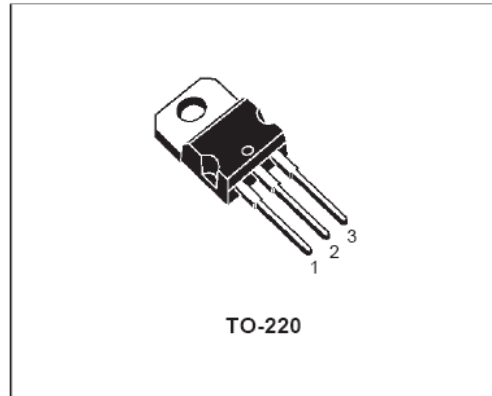
- TYPICAL R<sub>DS(on)</sub> = 0.75 Ω
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- VERY LOW INTRINSIC CAPACITANCES
- GATE CHARGE MINIMIZED

### DESCRIPTION

This power MOSFET is designed using the company's consolidated strip layout-based MESH OVERLAY™ process. This technology matches and improves the performances compared with standard parts from various sources.

### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVER



### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	500	V
V <sub>DGR</sub>	Drain- gate Voltage (R <sub>GS</sub> = 20 kΩ)	500	V
V <sub>GS</sub>	Gate-source Voltage	± 20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 25 °C	8.0	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 100 °C	5.1	A
I <sub>DM</sub> (●)	Drain Current (pulsed)	32	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	125	W
	Derating Factor	1.0	W/°C
dv/dt(1)	Peak Diode Recovery voltage slope	3.5	V/ns
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
T <sub>j</sub>	Max. Operating Junction Temperature	150	°C

(●) Pulse width limited by safe operating area (1) I<sub>SD</sub> ≤ 8A, di/dt ≤ 100 A/μs, V<sub>DD</sub> ≤ V<sub>BR,DSS</sub>, T<sub>J</sub> ≤ T<sub>J,MAX</sub>  
First Digit of the Datecode Being Z or K Identifies Silicon Characterized in this Datasheet

## IRF840

### THERMAL DATA

$R_{thj-case}$	Thermal Resistance Junction-case	Max	1.0	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max	62.5	°C/W
$R_{thc-sink}$	Thermal Resistance Case-sink	Typ	0.5	°C/W
$T_l$	Maximum Lead Temperature For Soldering Purpose		300	°C

### AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
$I_{AR}$	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max)	8.0	A
$E_{AS}$	Single Pulse Avalanche Energy (starting $T_j = 25$ °C, $I_D = I_{AR}$ , $V_{DD} = 50$ V)	520	mJ

### ELECTRICAL CHARACTERISTICS ( $T_{case} = 25$ °C unless otherwise specified)

#### OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250$ $\mu$ A $V_{GS} = 0$	500			V
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}$ $T_c = 125$ °C			1 50	$\mu$ A $\mu$ A
$I_{GSS}$	Gate-body Leakage Current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20$ V			$\pm 100$	nA

#### ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250$ $\mu$ A	2	3	4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10$ V $I_D = 4.8$ A		0.75	0.85	$\Omega$
$I_{D(on)}$	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10$ V	8.0			A

#### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}$ (*)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 4.8$ A	4.9			S
$C_{iss}$	Input Capacitance	$V_{DS} = 25$ V $f = 1$ MHz $V_{GS} = 0$		1300		pF
$C_{oss}$	Output Capacitance			200		pF
$C_{rss}$	Reverse Transfer Capacitance			18		pF



**ELECTRICAL CHARACTERISTICS** (continued)

**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 250\text{ V}$ $I_D = 4.3\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 3)		19		ns
$t_r$	Rise Time			11		ns
$Q_g$	Total Gate Charge	$V_{DD} = 400\text{ V}$ $I_D = 8.0\text{ A}$ $V_{GS} = 10\text{ V}$		39	50	nC
$Q_{gs}$	Gate-Source Charge			10.6		nC
$Q_{gd}$	Gate-Drain Charge			13.7		nC

**SWITCHING OFF**

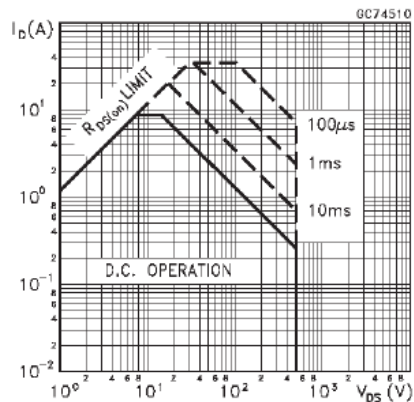
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$	Off-voltage Rise Time	$V_{DD} = 400\text{ V}$ $I_D = 8\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 5)		11.5		ns
$t_f$	Fall Time			11		ns
$t_c$	Cross-over Time			20		ns

**SOURCE DRAIN DIODE**

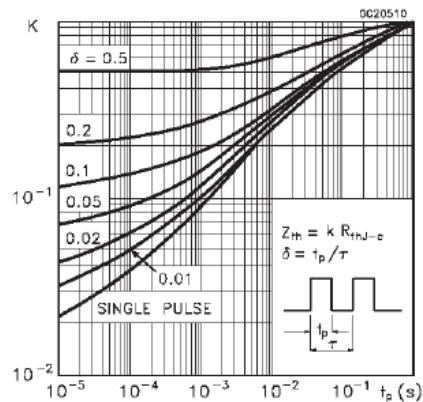
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain Current				8.0	A
$I_{SDM}(\bullet)$	Source-drain Current (pulsed)				32	A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 8.0\text{ A}$ $V_{GS} = 0$			1.6	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 8.0\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$ (see test circuit, figure 5)		420		ns
$Q_{rr}$	Reverse Recovery Charge			3.5		$\mu\text{C}$
$I_{RRM}$	Reverse Recovery Current			16.5		A

(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %  
( $\bullet$ ) Pulse width limited by safe operating area

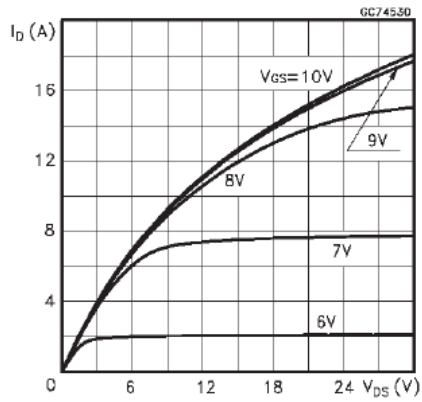
**Safe Operating Area**



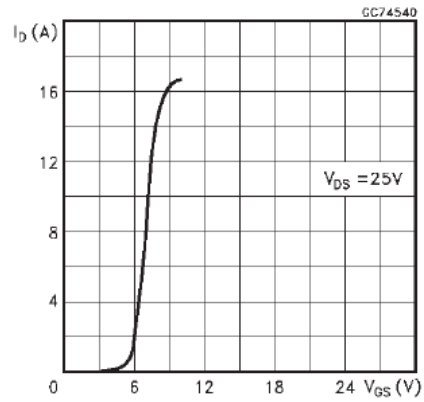
**Thermal Impedance**



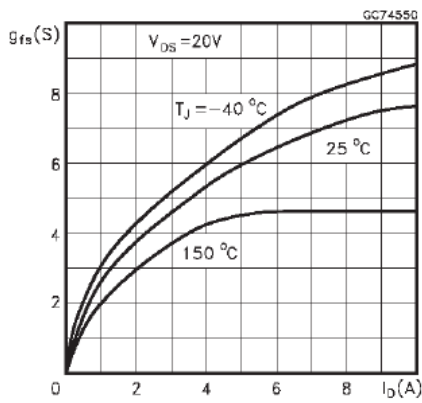
Output Characteristics



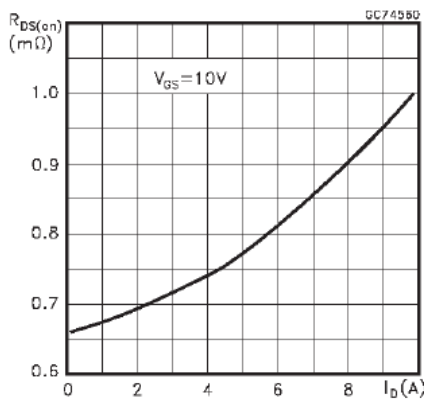
Transfer Characteristics



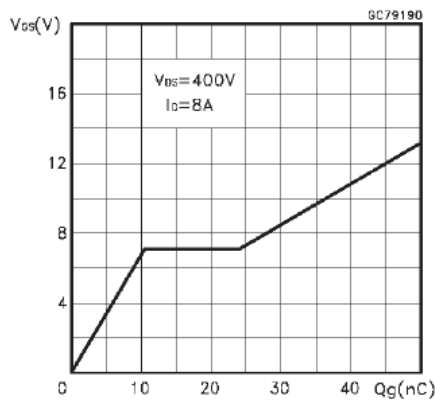
Transconductance



Static Drain-source On Resistance



Gate Charge vs Gate-source Voltage



Capacitance Variations

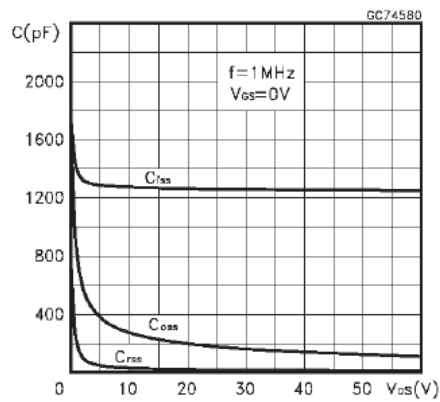


Fig. 1: Unclamped Inductive Load Test Circuit

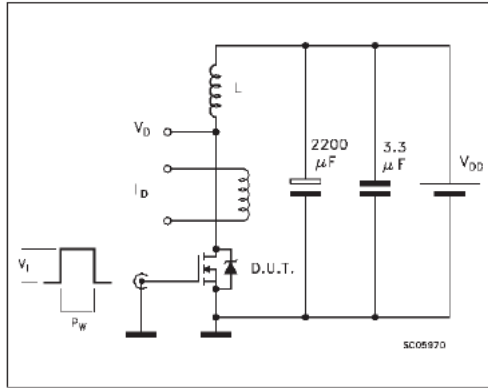


Fig. 1: Unclamped Inductive Waveform

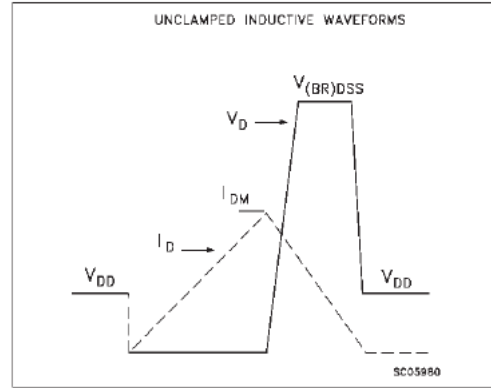


Fig. 3: Switching Times Test Circuits For Resistive Load

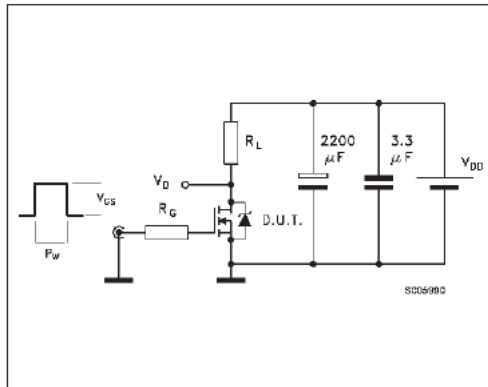


Fig. 4: Gate Charge test Circuit

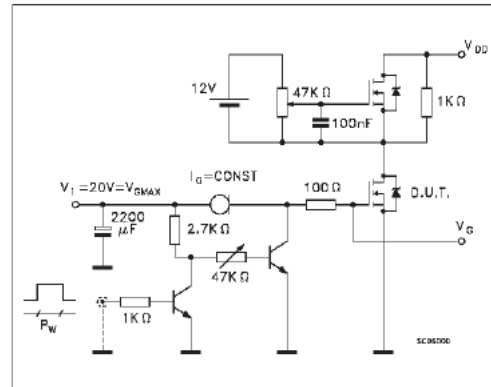
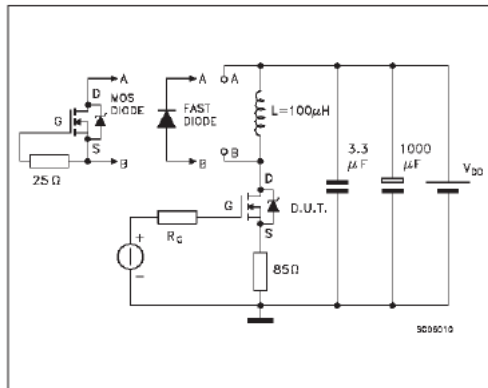
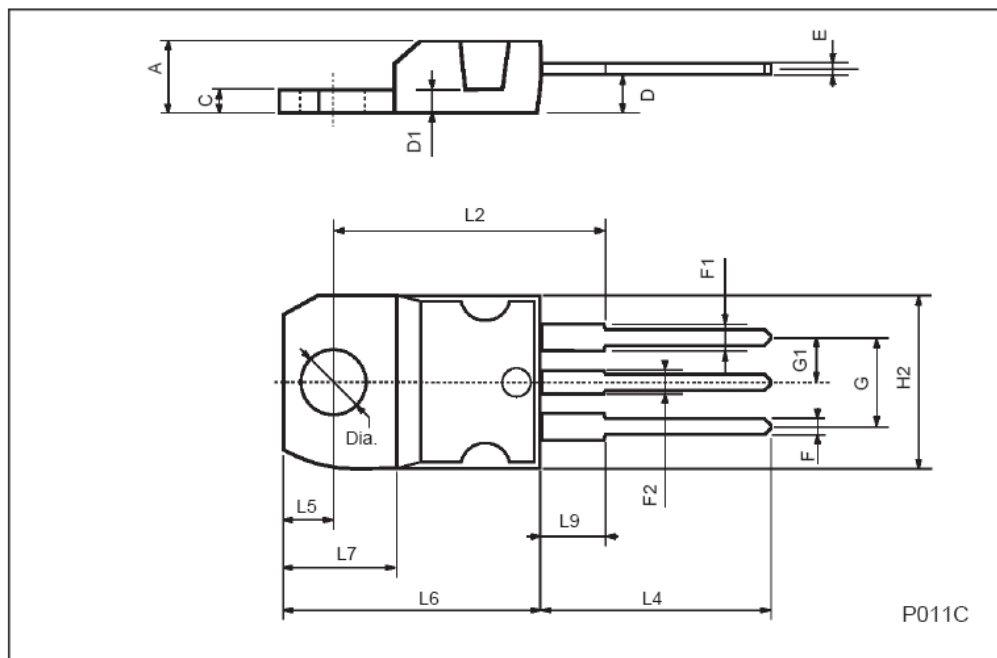


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



TO-220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



P011C

